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**MAR 20 2008**

Appl. No. 10/815,164  
Response Dated March 20, 2008  
Reply to Office Action of November 20, 2007

**Pending Claims:**

This listing will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

Claim 1 (Previously presented): A metal laminate manufactured by laminating a single layer of a polyimide copolymer to a metallic foil which metal laminate is subjected to an etching process to remove a portion of the metallic foil said etching process being conducted after the single layer of the polyimide copolymer is laminated to the metallic foil, said polyimide copolymer comprising two kinds of tetracarboxylic acid dianhydrides consisting of (A) isopropylidenebis(4-phenyleneoxy-4-phthalic acid) dianhydride and (B) 3,3', 4,4' -biphenyltetracarboxylic acid dianhydride, and (C) 6-amino-2-(p-aminophenyl)- benzimidazole and said polyimide copolymer being resistant to curling resulting from the metal laminate etching process so that the resulting etched metal laminate is substantially curl-free.

Claim 2 (Previously presented): A metal laminate according to claim 1, wherein the copolymer has a film formability.

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**Claim 3 (Previously presented):** A metal laminate according to Claim 1, wherein the two kinds of tetracarboxylic acid dianhydrides are used in a proportion of component (A) to component (B) of 10 – 80 mol.% to 90 – 20 mol.%.

**Claim 4 (Canceled)**

**Claim 5 (Canceled):**

**Claim 6 (Previously presented):** A metal laminate according to Claim 1 for use as a flexible printed circuit board.

**Claim 7 (Previously presented):** A metal laminate manufactured by laminating a single layer of a polyimide copolymer to a metallic foil which metal laminate is subjected to an etching process to remove a portion of the metallic foil said etching process being conducted after the single layer of the polyimide copolymer is laminated to the metallic foil, said polyimide copolymer comprising two kinds of tetracarboxylic acid dianhydrides consisting of (A) isopropylidenebis(4-phenyleneoxy-4-phthalic acid) dianhydride and (B) 3,3', 4, 4'-biphenyltetracarboxylic acid dianhydride, and two or three kinds of diamines consisting of (C) 6-amino-2-(p-aminophenyl) benzimidazole and (D) at least one kind of diamines consisting of bis(4-aminophenyl) ether (D<sub>1</sub>) and phenylenediamine (D<sub>2</sub>) and said polyimide copolymer being resistant to curling resulting from

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the metal laminate etching process so that the resulting etched metal laminate is substantially curl-free.

**Claim 8 (Previously presented):** A metal laminate according to Claim 7, wherein the copolymer has a film formability.

**Claim 9 (Previously presented):** A metal laminate according to Claim 7, wherein the two kinds of tetracarboxylic acid dianhydrides are used in a proportion of component (A) to component (B) of 10 – 80 mol% to 90 – 20 mol% and the diamines are used in a proportion of component (C) to component (D<sub>1</sub>) of not less than 60 mol.% to not more than 40 mol.%.

**Claim 10 (Previously presented):** A metal laminate according to Claim 7, wherein the two kinds of tetracarboxylic acid dianhydrides are used in a proportion of component (A) to component (B) of 10 – 80 mol% to 90 – 20 mol.%, and the diamines are used in a proportion of component (C) to component (D<sub>2</sub>) of not less than 20 mol.% to not more than 80 mol.%.

**Claims 11-14 (Canceled)**

**Claim 15 (Previously presented):** A metal laminate according to Claim 7 for use as a flexible printed circuit board.

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Claim 16 (Canceled)

Claim 17 (Previously presented): A process for manufacturing a metal laminate laminated with a single polyimide copolymer layer, said process comprising the steps of:

- a) subjecting two kinds of tetracarboxylic acid dianhydrides consisting of (A) isopropylidenebis (4-phenyleneoxy-4-phthalic acid) dianhydride and (B) 3,3', 4,4' - biphenyltetracarboxylic acid dianhydride to reaction with one kind of diamine consisting of (C) 6-amino-2-(p-aminophenyl) benzimidazole or two or three kinds of diarnines consisting of component (C) and (D) at least one kind of diamines consisting of bis(4-aminophenyl) ether (D<sub>1</sub>) and phenylenediamine (D<sub>2</sub>) in a polar solvent to form a solution of polyamic acid;
- b) applying the resulting solution of polyamic acid in the polar solvent from step a) to a metallic foil;
- c) drying the solvent off and heating the polyamic acid to a polyimidization reaction temperature to form a metal laminate; and
- d) subjecting the metal laminate to an etching process in which a portion of the metallic foil is etched and in which the polyimide copolymer layer resists and does not exhibit curling.